Lecture 8 MOSFET(I) MOSFET I-V CHARACTERISTICS

Outline

- 1. MOSFET: cross-section, layout, symbols
- 2. Qualitative operation
- 3. I-V characteristics

Reading Assignment: Howe and Sodini, Chapter 4, Sections 4.1-4.3

6.012 Spring 2009

Lecture 8



Key elements:

- Inversion layer under *gate* (depending on gate voltage)
- Heavily doped regions reach underneath gate \Rightarrow
 - inversion layer to electrically connect *source* and *drain*
- 4-terminal device:
 - *body* voltage important

Circuit symbols

Two complementary devices:

- n-channel device (n-MOSFET) on p-substrate
 - uses electron inversion layer
- p-channel device (p-MOSFET) on n-substrate
 - uses hole inversion layer



2. Qualitative Operation

- **Drain Current** (I_D) : proportional to inversion charge and the velocity that the charge travels from source to drain
- *Velocity*: proportional to electric field from drain to source
- Gate-Source Voltage (V_{GS}): controls amount of inversion charge that carries the current
- **Drain-Source Voltage** (V_{DS}) : controls the electric field that drifts the inversion charge from the source to drain



Want to understand the relationship between the *drain current* in the MOSFET as a function of *gate-to-source voltage* and *drain-to-source voltage*.

Initially consider source tied up to body (substrate or back)

Three Regions of Operation: Cut-off Region

- MOSFET:
 - V_{GS} < V_T, with V_{DS} \ge 0
- Inversion Charge = 0
- V_{DS} drops across drain depletion region
- $I_D = 0$



Three Regions of Operation: Linear or Triode Region



 $V_{GD} = V_{GS} - V_{DS}$

Electrons drift from source to drain \Rightarrow electrical current!

•
$$V_{GS} \uparrow \Rightarrow |Q_N| \uparrow \Rightarrow I_D \uparrow$$

• $V_{DS} \uparrow \Rightarrow E_y, \uparrow \Rightarrow I_D \uparrow$ $V_{DS} << V_{GS} - V_T$

'y'





3. I-V Characteristics (Assume V_{SB}=0)

Geometry of problem:



All voltages are referred to the *Source*

General expression of channel current

Current can only flow in the y-direction:

Total channel flux:

$$I_{y} = W \bullet Q_{N}(y) \bullet v_{y}(y)$$

Drain current is equal to minus channel current:

$$I_D = -W \bullet Q_N(y) \bullet v_y(y)$$

I-V Characteristics (Contd.)

$$I_D = -W \bullet Q_N(y) \bullet v_y(y)$$

Re-write equation in terms of voltage at location y, V(y):

• If electric field is not too high:

$$v_y(y) = -\mu_n \bullet E_y(y) = \mu_n \bullet \frac{dV}{dy}$$

• For $Q_N(y)$, use charge-control relation at location y:

$$Q_N(y) = -C_{ox} \left[V_{GS} - V(y) - V_T \right]$$

for $V_{GS} - V(y) \ge V_{T}$.

Note that we assumed that V_T is independent of y. See discussion on <u>body effect</u> in Section 4.4 of text.

All together the drain current is given by:

$$I_D = W \bullet \mu_n C_{ox} \left[V_{GS} - V(y) - V_T \right] \bullet \frac{dV(y)}{dy}$$

Simple linear first order differential equation with one un-known, the channel voltage V(y).

I-V Characteristics (Contd..)

Solve by separating variables:

$$I_D dy = W \bullet \mu_n C_{ox} \left[V_{GS} - V(y) - V_T \right] \bullet dV$$

Integrate along the channel in the linear regime subject the boundary conditions :

Then:

$$I_D \int_0^L dy = W \bullet \mu_n C_{ox} \int_0^{V_{DS}} [V_{GS} - V(y) - V_T] \bullet dV$$

Resulting in:

$$I_D[y]_0^L = I_D L = W \bullet \mu_n C_{ox} \left[\left(V_{GS} - \frac{V}{2} - V_T \right) V \right]_0^{V_{DS}}$$

$$I_D = \frac{W}{L} \bullet \mu_n C_{ox} \left[V_{GS} - \frac{V_{DS}}{2} - V_T \right] \bullet V_{DS}$$

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I-V Characteristics (Contd...)

$$I_D = \frac{W}{L} \bullet \mu_n C_{ox} \left[V_{GS} - \frac{V_{DS}}{2} - V_T \right] \bullet V_{DS}$$

for $V_{DS} < V_{GS} - V_T$

Key dependencies:

- V_{DS}↑ → I_D↑ (higher lateral electric field)
 V_{GS}↑ → I_D↑ (higher electron concentration)



This is the *linear* or *triode* region: It is linear if $V_{DS} \ll V_{GS} - V_T$

I-V Characteristics (Contd....) Two important observations

1. Equation only valid if $V_{GS} - V(y) \ge V_T$ at *every* y. Worst point is y=L, where $V(y) = V_{DS}$, hence, equation is valid if

$$V_{DS} \leq V_{GS} - V_T$$



I-V Characteristics (Contd.....) Two important observations

2. As V_{DS} approaches $V_{GS} - V_T$, the rate of increase of I_D decreases.

Reason:

As y increases down the channel, $V(y) \uparrow$, $|Q_N(y)| \downarrow$, and $E_v(y) \uparrow$ (*fewer carriers moving faster*)

- \Rightarrow inversion layer thins down from source to drain
- \Rightarrow I_D grows more slowly.



I-V Characteristics (Contd.....) Drain Current Saturation

As V_{DS} approaches

$$V_{DSsat} = V_{GS} - V_T$$

increase in E_y compensated by decrease in $|Q_N| \Rightarrow I_D$ saturates when $|Q_N|$ equals 0 at drain end.

Value of drain saturation current:

$$I_{Dsat} = I_{Dlin}(V_{DS} = V_{DSsat} = V_{GS} - V_T)$$

Then

$$I_{Dsat} = \left\lfloor \frac{W}{L} \bullet \mu_n C_{ox} \left(V_{GS} - \frac{V_{DS}}{2} - V_T \right) \bullet V_{DS} \right\rfloor_{V_{DS} = V_{GS} - V_T}$$

$$I_{Dsat} = \frac{1}{2} \frac{W}{L} \mu_n C_{ox} \left[V_{GS} - V_T \right]^2$$

Will talk more about *saturation region* next time.

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I-V Characteristics (Contd.....)

Output Characteristics



Transfer characteristics:



Output Characteristics



Summary of Key Concepts

• **MOSFET Output Characteristics**



I-V Characteristics in Cutoff Region $V_{GS} < V_T I_D = 0$

I-V Characteristics in Linear Region $V_{DS} < V_{GS} - V_{T}$ $I_{D} = \frac{W}{L} \bullet \mu_{n} C_{ox} \left[V_{GS} - \frac{V_{DS}}{2} - V_{T} \right] \bullet V_{DS}$ I-V Characteristics in Saturation Region $V_{DS} \ge V_{GS} - V_{T}$ $I_{DSat} = \frac{W}{2L} \mu_{n} C_{ox} \left(V_{GS} - V_{T} \right)^{2}$ 6.012 Microelectronic Devices and Circuits Spring 2009

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